

Material Composition Specification

SMB Case

Pb (lead)-free plating**



Device average mass **92 mg**

Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.8%	0.76	Si	7440-21-3	0.8%	0.76	8,000
leadframe	copper	37.04%	34.04	Cu	7440-50-8	37.04%	34.04	370,400
die attach	high temperature solder paste	2.446%	2.25	Pb	7439-92-1	2.262%	2.081	22,620
				Sn	7440-31-5	0.122%	0.113	1,220
				Ag	7440-22-4	0.061%	0.056	610
encapsulation*	EMC	58.95%	54.23	silica	7631-86-9	40.086%	36.879	400,860
				epoxy resin	Proprietary	17.685%	16.27	176,850
				Sb ₂ O ₃	1309-64-4	0.59%	0.542	5,900
				TBBA	79-94-7	0.59%	0.542	5,900
	EMC GREEN	58.95%	54.23	silica	7631-86-9	40.9%	37.631	409,048
				epoxy resin	Proprietary	18.05%	16.602	180,462
plating**	tin lead process	0.89%	0.606	Sn	7440-31-5	0.616%	0.566	6,160
				Pb	7439-92-1	0.154%	0.142	1,540
	100% tin process	0.77%	0.708	Sn	7440-31-5	0.77%	0.708	7,700

*EMC GREEN molding compound is Halogen-Free.

**Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

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